Device Material Content

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Package: 64 QFNS
Total Device Weight 0.240 Grams

Package Code: SN64
Products: ispPAC-CLK

Assembly: Unisem
Size (mm): 9 x 9 x 0.9
Lead pitch (mm): 0.5
MSL: 3
Reflow max (ºC): 260

	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (g)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	2.18%	0.0052	2.18%	0.0052	Silicon chip	7440-21-3	100.00%	Die size: 3.0 x 3.0 mm
Mold Compound	51.46%	0.1235	45.29%	0.1087	Silica (fused)	60676-86-0	88.00%	Mold Compound: Sumitomo EME-G770
			2.57%	0.0062	Epoxy Resin	-	5.00%	
			2.57%	0.0062	Phenol Resin	-	5.00%	
			0.90%	0.0022	Metal Hydroxide	-	1.75%	
			0.13%	0.0003	Carbon Black	1333-86-4	0.25%	
D/A Epoxy	0.38%	0.0009	0.29%	0.00069	Silver	7440-22-4	75.00%	Die attach: Sumitomo CRM1066 series
			0.04%	0.00009	Epoxy Resin A	9003-36-5	10.00%	
			0.06%	0.00014	Esters & resins	-	15.00%	
Wire	0.60%	0.0014	0.60%	0.0014	Gold (Au)	7440-57-5	100.00%	0.8 mil wire diameter; 1 wire for each package lead
Plating	0.28%	0.0007	0.28%	0.0007	Tin (Sn)	7440-31-5	100.00%	Plating is 100% Matte Sn; thickness is >10.2µm
Leadframe	45.09%	0.1082	43.60%	0.1046	Copper (Cu)	7440-50-8	96.70%	C7025
			1.36%	0.0033	Nickel (Ni)	7440-02-0	3.01%	
			0.08%	0.0002	Silicon (Si)	7440-21-3	0.17%	
			0.01%	0.0000	Magnesium (Mg)	7439-95-4	0.03%	
			0.04%	0.0001	Silver (Ag)	7440-22-4	0.09%	

Notes:
The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.
Constituent substances and proportions in epoxy materials are before curing.
The information provided above is representative of the package as of the date listed, and is subject to change at any time.
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Rev. C